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Part Number:	0762910250			
Status:	Active			
ACLIVE				
Overview:	EdgeLine High Speed Conn			and the second
Description:				and the second se
	Circuits			The second se
				A DESCRIPTION OF THE OWNER OWNER OF THE OWNER
Documents:				
<u>3D Model</u>		Application Specification AS-76291-002-001 (PDF)	Series imag	e - Reference only
Drawing (PDF)		Packaging Specification PK-76291-001 (PDF)		
	n PS-76291-001-001 (PDF)	RoHS Certificate of Compliance (PDF)	EU EL V	
Application Specifica	ation AS-76291-001-001 (PDF)		EU ELV Not Relevant	
			Not Relevant	
General			EU RoHS	China RoHS
Product Family		Edge Card Connectors	Compliant	
Series		<u>76291</u>	REACH SVHC	
Application Tooling I	Part Link	62202-2802	Not Contained Per	-
Component Type		Edgecard to PCB	ED/61/2018 (27 Ju	
Data Rate		5.0-12.0 Gbps	2018)	
Edge Card Thicknes		1.57mm	Halogen-Free	
High Power Bay (30	.0A or more)	No	Status	
Orientation		Coplanar	Low-Halogen	
Overview		EdgeLine High Speed Connectors		on, please visit <u>Contact US</u>
Product Name		EdgeLine		, presee
Standard Based		General	China ROHS	Green Image
UPC		883906484934	ELV	Not Relevant
Physical			RoHS Phthalates	Not Contained
(p)ower-(s)ignal Cor	ofiguration	250s - 0p		
Circuit Size Range	ingeretion	201-294 Circuits		
Circuits (Loaded)		250	Search Parts in this Series	
Circuits (maximum)		250	76291 Series	
Color - Resin		Black	eenee	
Durability (mating cy	(cles max)	200	Application Too	
Entry Angle		N/A	Application Too	tions and manuals are
Keying to Mating Pa	irt	N/A		g the products below.
Material - Metal		Copper Alloy		- , , , , , , , , , , , , , , , , , , ,
Material - Plating Mating		Gold over Nickel	Crimp Height Specifications are then contained in the Application Tooling	
Material - Plating Te		Tin	Specification doc	
Material - Resin		High Temperature Thermoplastic	Global	ument.
Net Weight		31.477/g	Description	Product #
PCB Locator		No	Press-In Tool for	0622022802
PCB Thickness - Re	commended	2.79mm	12.5 Gbps Copla	
Packaging Type		Tray		
Pitch - Mating Interfa	ace	0.75mm		
Pitch - Termination I		0.75mm		
Plating min - Mating		0.762µm		
Plating min - Termin		0.762µm		
Polarized to Mating		Yes		
Temperature Range		-40° to +85°C		
Termination Interfac		Through Hole - Compliant Pin		
Electrical	n en Oantest			
Current - Maximum	perContact	1.5A		

1.5A 50V AC (RMS)/DC

N/A

Voltage - Maximum

Solder Process Data Lead-freeProcess Capability

Material Info

Reference - Drawing Numbers Application Specification Packaging Specification Product Specification S-Parameter Model Sales Drawing

AS-76291-001-001, AS-76291-002-001 PK-76291-001 PS-76291-001-001 SP-76291-0002 SD-76291-001

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